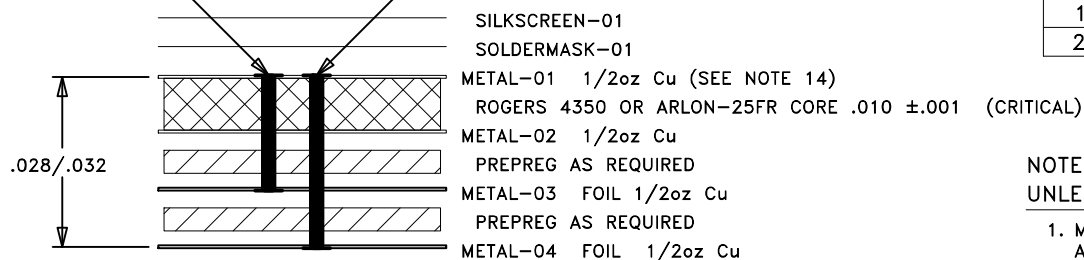
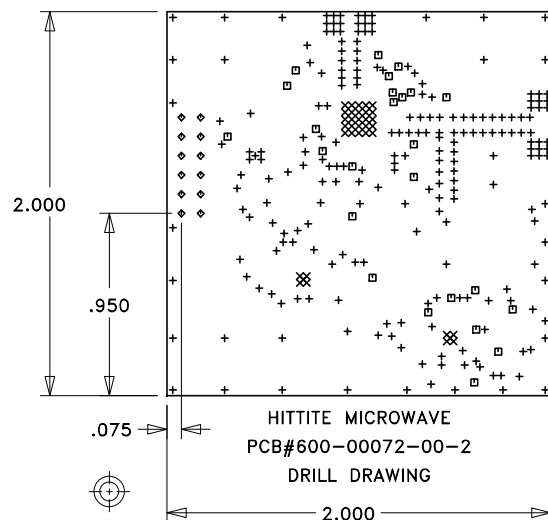


BLIND VIAS
SEE NOTE 15

THRU VIAS



LAYER STACKUP



SIZE	QTY	SYM	PLATED	THR/PRTL	TOL
10	35	✕	YES	THR	+/-3
14	25	□	YES	P1-3	+/-3
14	225	+	YES	THR	+/-3
40	12	◇	YES	THR	+/-3

SEE NOTE 20

SEE NOTE 20

UNLESS OTHERWISE SPECIFIED:

DIMENSIONS ARE IN INCHES [mm]

DRAWING PRACTICES
PER ASME Y14.100

INTERPRET
DIMENSIONS & TOLERANCES
PER ASME Y14.5-2009

TOLERANCES:

.XX ± .01
.XXX ± .005
.XXX ± .0020
ANGLES ± .5 DEG.

NEXT ASSY

USED ON

REVISION

LTR	DESCRIPTION	DATE	APPROVED
1	ENGINEERING RELEASE	01/04/11	M.LYONS
2	ADD C71-72,DEL R6-R7,CHG C34 CONN	06/09/11	M.LYONS

NOTES:

UNLESS OTHERWISE SPECIFIED:

- MATERIAL: MULTILAYER. OVERALL STACKUP AS SHOWN. TYPE ROGERS 4350 OR ARLON 25FR, HALF OUNCE COPPER BOTH SIDES. FR4 TO BE USED AS FILLER TO MEET CRITICAL OVERALL THICKNESS.
- ENIG (Electroless Nickel/Immersion Gold)
100 MICRO INCHES NICKEL/3-5 MICRO INCHES GOLD
- PLATED THRU HOLES: .001 MINIMUM WALL THICKNESS.
- HOLE SIZES AND POSITIONS PER ARTWORK AND/OR DRILL FILE.
- ALL HOLES TO BE LOCATED WITHIN ±.003 OF THE CENTER OF THE PAD OR OTHER TRUE POSITION.
- FRONT TO BACK REGISTRATION ±.003 MAX.
- BOARD WARPAGE: <.010 PER LINEAR INCH.
- SILKSCREEN TOP SIDE ONLY WITH WHITE EPOXY INK.
- SOLDERMASK: LPI SOLDERMASK TOP SIDE. COLOR: GREEN REGISTRATION: ±.004 MAX.
- "SIZE" IN DRILL LEGEND IS IN MILS AND REFERS TO FINISHED HOLE SIZE.
- MANUFACTURE PER IPC-6012 CLASS 2.
- PLATING THICKNESS .002 ±.0005 FOR METAL-01 AND METAL-04.
- ARTWORK IS 1:1. VENDOR TO ADJUST FOR ETCH FACTOR.

SPECIAL REQUIREMENTS:

- CRITICAL LINE WIDTH = .016 ±.001 ON METAL-01. ADJUST PROCESS TO ACHIEVE WIDTH.
- BLIND VIAS: METAL LAYERS 1 - 3 PER DRILL FILE.

VENDOR NOTES:

- VENDOR TO COMPARE IPC NET LIST TO GERBER FILES FOR CONTINUITY. ANY DISCREPANCIES MUST BE REPORTED TO HITTITE MICROWAVE.
- VENDOR MAY ADD E-TEST STAMP TO PCB. VENDOR SHALL NOT ADD NAME, LOGO, DATE CODE, UL LISTING OR ANY OTHER MARKING TO ANY VISIBLE LAYER.
- BOARDS MUST PASS VISUAL INSPECTION PER IPC-A-600 CLASS 2.
- FINISHED BOARDS ARE TO BE BARE BOARD TESTED.
- VIAS INDICATED TO BE FILLED WITH NON-CONDUCTIVE EPOXY AND GRIND FLUSH PRIOR TO OVERPLATING.

PROPRIETARY TO HITTITE MICROWAVE CORPORATION



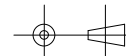
HITTITE MICROWAVE CORPORATION

20 Alpha Road
Chelmsford, MA 01824

TITLE

PCB, EVAL

THIRD ANGLE
PROJECTION



DO NOT SCALE DRAWING

SIZE	CODE ID NO.	DWG NO.	REV
A	1CN88	600-00072-00	2
SCALE: 1:1		WT:	SHEET: 1 OF 1